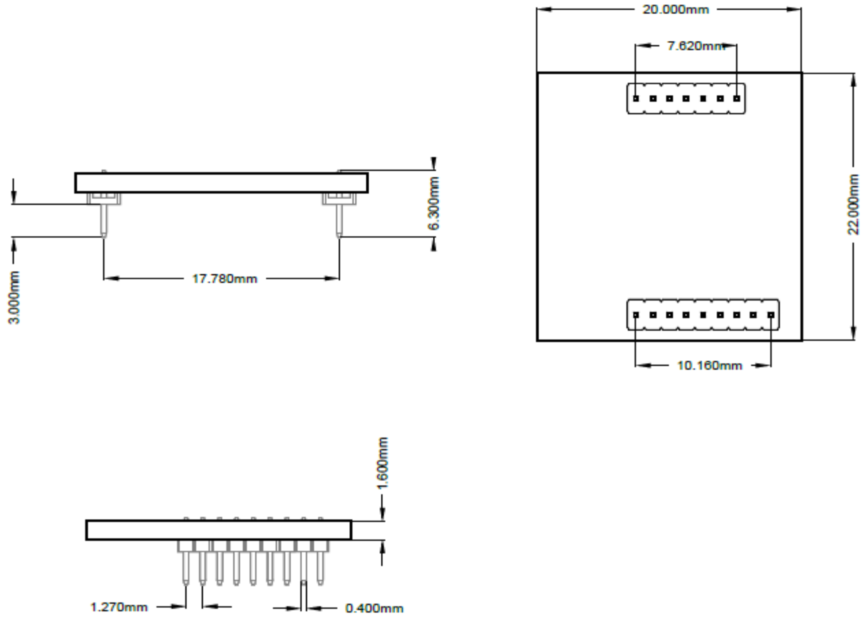
BHI260AP
Shuttle board 3.0 flyer

1 General description

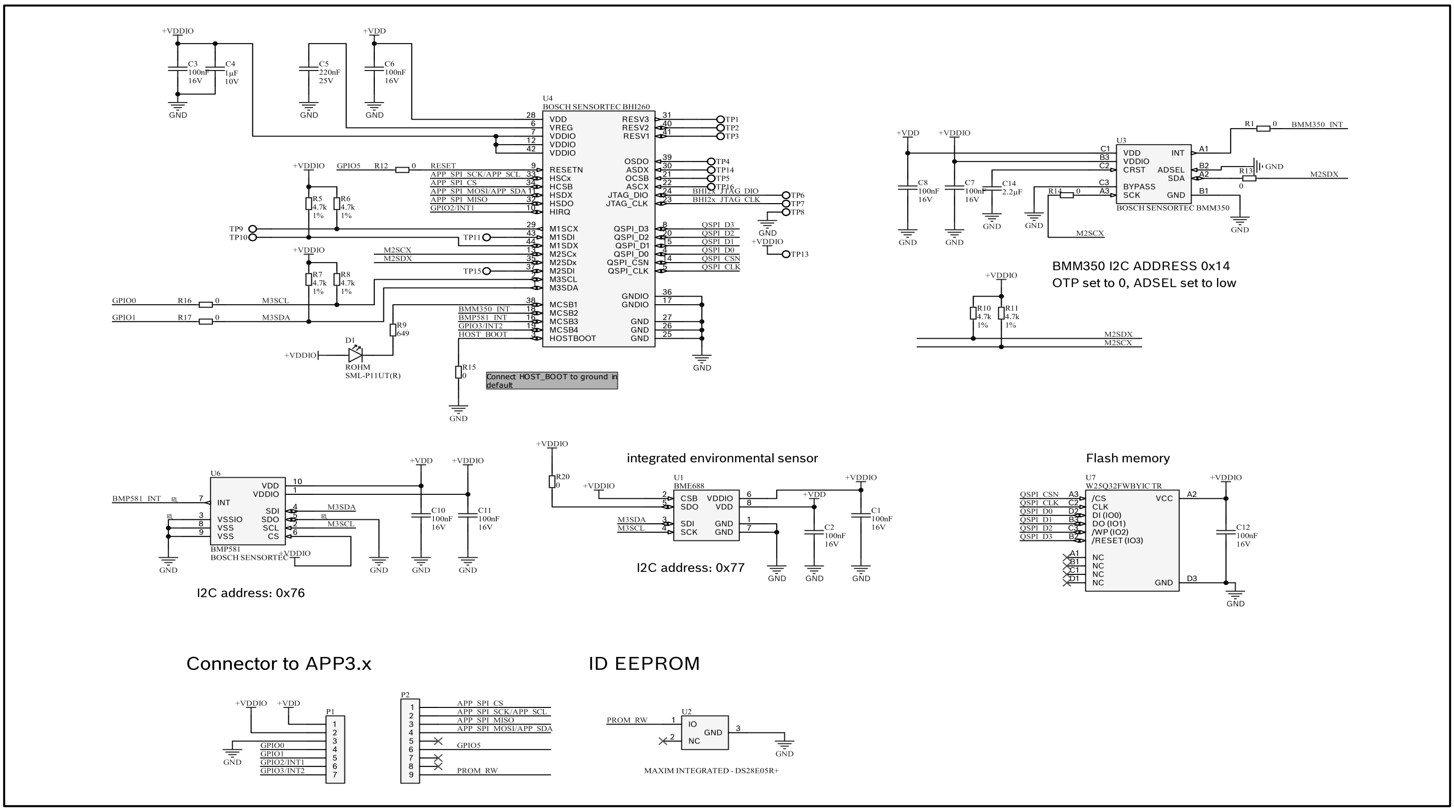
The Bosch Sensortec BHI260AP shuttle board 3.0 is a PCB with the smart sensor BHI260AP mounted on it. In combination with the Application Board 3.x, this shuttle board can be used to evaluate various functionalities provided on BHI260AP. The shuttle board allows easy access to the sensor pins via a simple socket and can be directly plugged into the Bosch Sensortec Application Board 3.x.
The shuttle board includes following major components:

- BHI260AP smart sensor
- BME688 environmental sensor (I2C interface)
- BM581 pressure sensor (I2C interface)
- BMM350 magnetometer (AUX Interface)
- W25Q32FW flash memory 4M (QSPI Interface)
- On-board EEPROM

BHI260AP Shuttle board 3.0
Note: Product photo may differ from real product's appearance



Shuttle board outline dimension
All dimensions in mm



Electrical layout

2 Designator P1 shuttle board connector

Pin	Pin name	Description
1	VDD	Analog power supply voltage (1.71V --- 3.6V)
2	VDDIO	Digital I/O power supply voltage (1.71V --- 1.89V)
3	GND	Ground
4	GPIO0	SCL pin of M3, with a 4.7 kΩ pull-up to 1.8V VDDIO
5	GPIO1	SDA pin of M3, with a 4.7 kΩ pull-up to 1.8V VDDIO
6	GPIO2/INT1	Host interrupt pin (connect to BHI260AP host interrupt
7	GPIO3/INT2	SPI chip select4/GPIO

3 Designator P2 shuttle board connector

Pin	Pin name	Description
1	CS	Chip selection pin of SPI bus
2	SCK/SCL	Clock pin of SPI bus / clock pin of I2C bus
3	SDO	Sensor Data Out pin of SPI bus
4	SDI/SDA	Serial Data In pin of SPI bus / data pin of I2C bus
5	GPIO4	NC
6	GPIO5	BHI260AP reset input, active low
7	GPIO6	NC
8	GPIO7	NC
9	PROM_RW	Connect to EEPROM

Shuttle board identification:

- Shuttle ID: 0x119
- Shuttle board identifier: BST01456

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